

REMARKS

Claims 27-53 are currently pending. Claims 1-26 have been canceled and (amended and unamended) were allowed in the parent case. Claims 42-44 and 46-47 have been cancelled. Claim 45 has been amended.

Objections to the Claims

Claims 27-31 and 48-51 were objected to. In particular, the Office Action states that Figure 6 does not disclose any filling material. Attention is drawn to the application at pg. 5, lines 14-24 where it is disclosed that the space between the conductive layer, the overcoat layer sections and the bonding pad is filled. In responding to the Restriction Requirement, Applicant stated that the claims at issue read on Fig. 6 among others. Accordingly, reconsideration and withdrawal of the objection to the claims is respectfully requested.

Rejection of the Claims under 35 U.S.C. § 103(a)

Claims 27-31, 42-44 and 48-51 were rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,065,505 to Matsubara et al. ("Matsubara") in view of U.S. Patent No. 5,641,996 to Omoya et al. ("Omoya") and U.S. Patent No. 5,611,884 to Bearinger et al. ("Bearinger").

Looking at independent claim 27, this claim recites that an overcoat layer is provided having at least two sections where bottom surfaces of each overlap partially and are to be pressed onto a top surface of the bonding pad. Claim 27 also requires that there be a "space" formed between the bonding pad, conductive layer and the at least two sections of the overcoat layer.

This space is to be occupied by a filling. This feature is clearly not shown in Matsubara.

Matsubara discloses an adhesive 8 that completely covers element 2 and the electrodes 6 attached thereto. Since the adhesive 8 completely covers element 2, it is not possible that that there is a “space formed by the at least one bonding pad, the conductive layer, and the at least two sections of the overcoat layer.” Accordingly, a feature of the claim is completely missing from Matsubara.

Omoya and Bearinger fail to make up for the deficiencies of Matsubara. In Omoya the encapsulant 7 is used to fill space between electrical connections. Those electrical connections are made without the benefit of an overcoat layer, in particular the one recited in the claims. Since no overcoat layer including two sections for partially overlapping a bonding pad is provided in Omoya, the “space” limitation as recited above is missing from Omoya as well.

Likewise, in Bearinger, no overcoat layer is provided, in particular, an overcoat layer as recited in the claims. Instead, a conductive adhesive surrounds a conductive ball to facilitate connection between two bonding pads. Since no overcoat layer is provided in Bearinger that includes two sections for partially overlapping a bonding pad, the “space” limitation recited above is missing from Bearinger as well.

Independent claim 48 includes overcoat layer and “space” limitations that are similar to what is found in claim 27. Since features of the claims are neither taught nor suggested by Matsubara, Omoya or Bearinger (taken singularly or in combination), reconsideration and withdrawal of the rejection of claims 27-31 and 48-51 under 35 U.S.C. § 103(a) is respectfully requested.

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Amendment dated May 30, 2006
Response to Office Action dated Dec. 30, 2005

CONCLUSION

The Examiner is invited to contact the undersigned at (202) 220-4255 to discuss any matter concerning this application. The Office is hereby authorized to charge any additional fees or credit any overpayments under 37 C.F.R. § 1.16 or § 1.17 to Deposit Account No. 11-0600.

Respectfully submitted,
KENYON & KENYON

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